

July 2013

# **FDP5800**

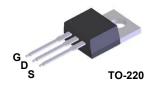
# N-Channel Logic Level PowerTrench $^{(\!R\!)}$ MOSFET 60V ,80 A, 6 m $_{\Omega}$

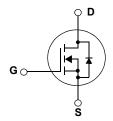
#### **Features**

- $R_{DS(on)}$  = 4.6 m $\Omega$  (Typ.),  $V_{GS}$  = 10 V,  $I_D$  = 80 A
- High Performance Trench Technology for Extermly Low  $R_{\mbox{\footnotesize{DS}}(\mbox{\footnotesize{on}})}$
- · Low Gate Charge
- · High Power and Current Handing Capability
- · RoHs Compliant

# **Applications**

- · Power tools
- · Motor drives and Uninterruptible Power Supplies
- · Synchronous Rectification
- · Battery Protection Circuit





# MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted\*

Symbol		Parameter	FDP5800	Unit
V <sub>DSS</sub>	Drain-Source Voltage	Drain-Source Voltage		V
V <sub>GSS</sub>	Gate-Source Voltage		±20	V
		-Continuous (T <sub>C</sub> = 25°C)	80	Α
$I_D$	Drain Current	-Continuous (T <sub>C</sub> = 100°C)	80*	Α
	-Continuous (T <sub>A</sub> = 25°C)	14	Α	
I <sub>DM</sub>	Drain Current - Pulsed		320	Α
E <sub>AS</sub>	Single Pulsed Avalanch	e Energy (Note 1)	652	mJ
$P_{D}$	Power Dissipation	242 1.61	W W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage	Temperature Range	-55 to +175	°C

\*Drain current limited by package

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance , Junction to Case, Max.	0.62	°C/W
$R_{\theta JA}$	Thermal Resistance , Junction to Ambient, Max.	62.5	°C/W

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP5800	FDP5800	TO220		-	50

# Electrical Characteristics $T_C$ = 25°C unless otherwise noted

Symbol	Parameter	Condition	s	Min	Тур	Max	Unit
Off Charac	eteristics						
B <sub>VDSS</sub>	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	/, T <sub>J</sub> =25°C	60			V
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 48V				1	μΑ
I <sub>DSS</sub> Zero Gate voltage Drain Current	$V_{GS} = 0V$	$T_J = 150$ °C			500	μΑ	
I <sub>GSS</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = \pm 20V, V_{DS} = 0$	V			±100	nA

#### **On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.0	-	2.5	٧
	$V_{GS} = 10V$ , $I_{D} = 80A$		4.6	6.0	$m\Omega$	
		$V_{GS} = 4.5 V$ , $I_{D} = 80 A$		5.9	7.2	mΩ
R <sub>DS(on)</sub>	Static Drain-Source On Resistance	V <sub>GS</sub> = 5V , I <sub>D</sub> = 80A		5.6	7.0	mΩ
		$V_{GS} = 10V, I_D = 80A$ $T_J = 175^{\circ}C$		10.4	12.6	mΩ

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	\/ 4F\/\/	0) (		6890	9160	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 15V, V_{GS} = 100$	UV		750	1000	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 11VII 12			295	445	pF
$R_G$	Gate Resistance	$V_{GS} = 0.5V, f = 1N$	ЛHz	-	1.2	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS}$ = 0V to 10V		-	112	145	nC
$Q_{g(TH)}$	Total Gate Charge at 5V	$V_{GS} = 0V \text{ to } 5V$	.,	-	58	-	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0V \text{ to } 1V$	$V_{DS} = 30V$ $I_{D} = 80A$	-	7.0	-	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>1</sub>	$I_0 = 30A$ $I_0 = 1mA$	-	23	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau		.g		13		nC
$Q_{gd}$	Gate to Drain "Miller" Charge				18		nC

# **Switching Characteristics (V<sub>GS</sub> = 10V)**

t <sub>ON</sub>	Turn-On Time		/	37	85	ns
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ = 30V, $I_{D}$ = 80A $V_{GS}$ = 10V, $R_{GEN}$ = 1.5 $\Omega$	/	18	46	ns
t <sub>r</sub>	Turn-On Rise Time			19	47	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			55	120	ns
t <sub>f</sub>	Turn-Off Fall Time			9	28	ns
t <sub>OFF</sub>	Turn-Off Time		-	64	138	ns

#### **Drain-Source Diode Characteristics**

V <sub>SD</sub> Drain-Source Diode Forward Voltage	Drain-Source Diode, Forward Voltage	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 80A	 	1.25	V
	$V_{GS} = 0V, I_{SD} = 40A$	 	1.0	V	
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 60A	 58		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	 106		nC

Notes: 1: L = 1mH,  $I_{AS}$  = 36A,  $V_{DD}$  = 54V,  $V_{GS}$  = 10V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

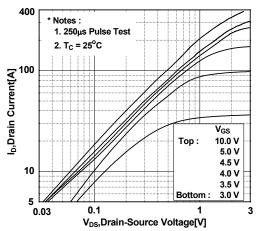


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

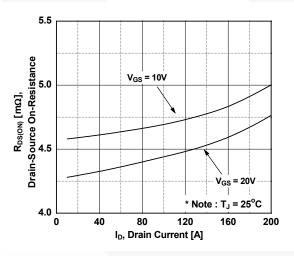


Figure 5. Capacitance Characteristics

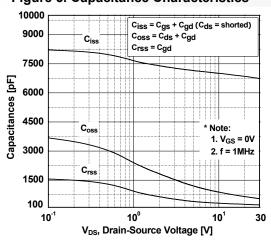


Figure 2. Transfer Characteristics

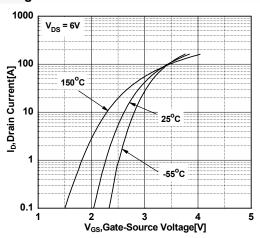


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

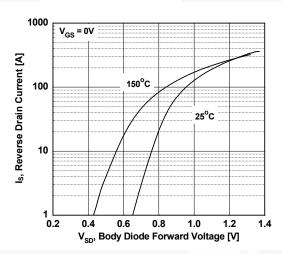
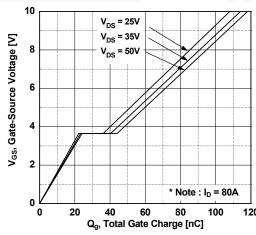


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

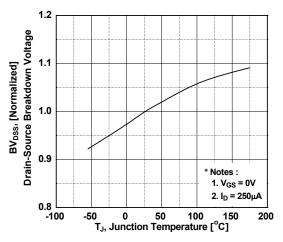


Figure 9. Maximum Safe Operating Area

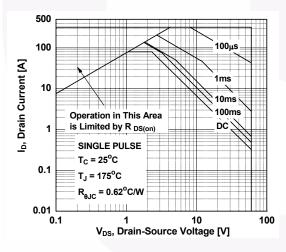


Figure 8. On-Resistance Variation vs. Temperature

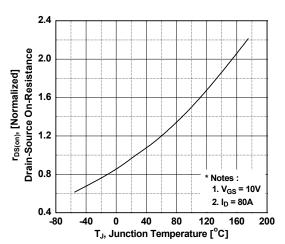


Figure 10. Maximum Drain Current vs. Case Temperature

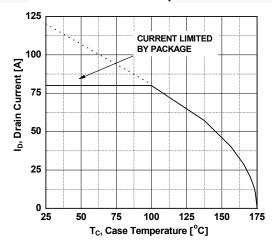


Figure 11. Transient Thermal Response Curve

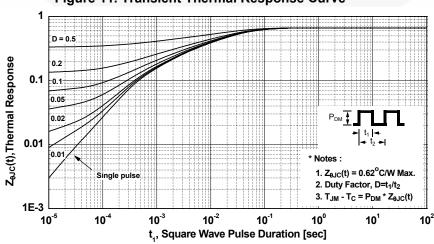


Figure 12. Gate Charge Test Circuit & Waveform

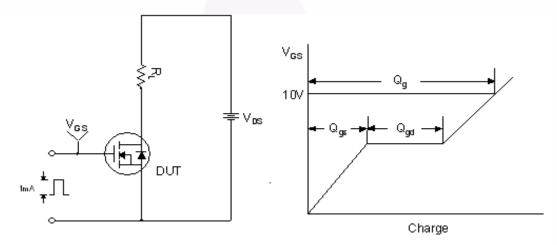


Figure 13. Resistive Switching Test Circuit & Waveforms

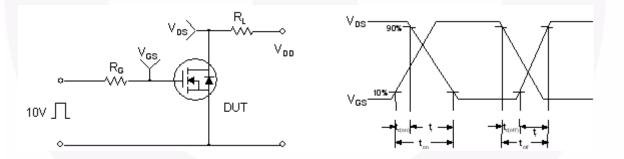
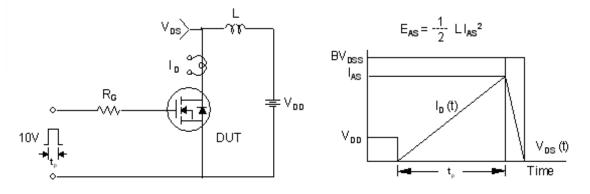


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



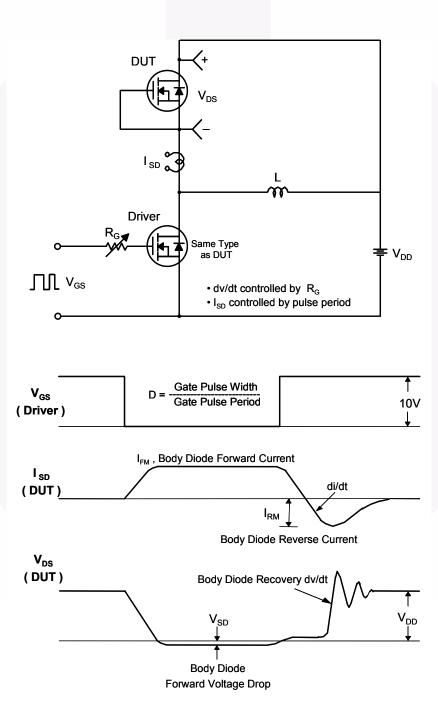


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

### **Physical Dimensions**

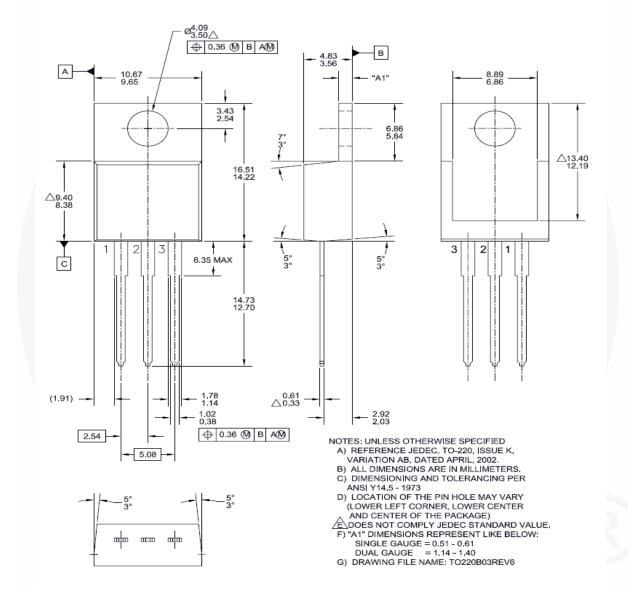


Figure 16. TO-220, MOLDED, 3LEAD, JEDEC VARIATION AB

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